



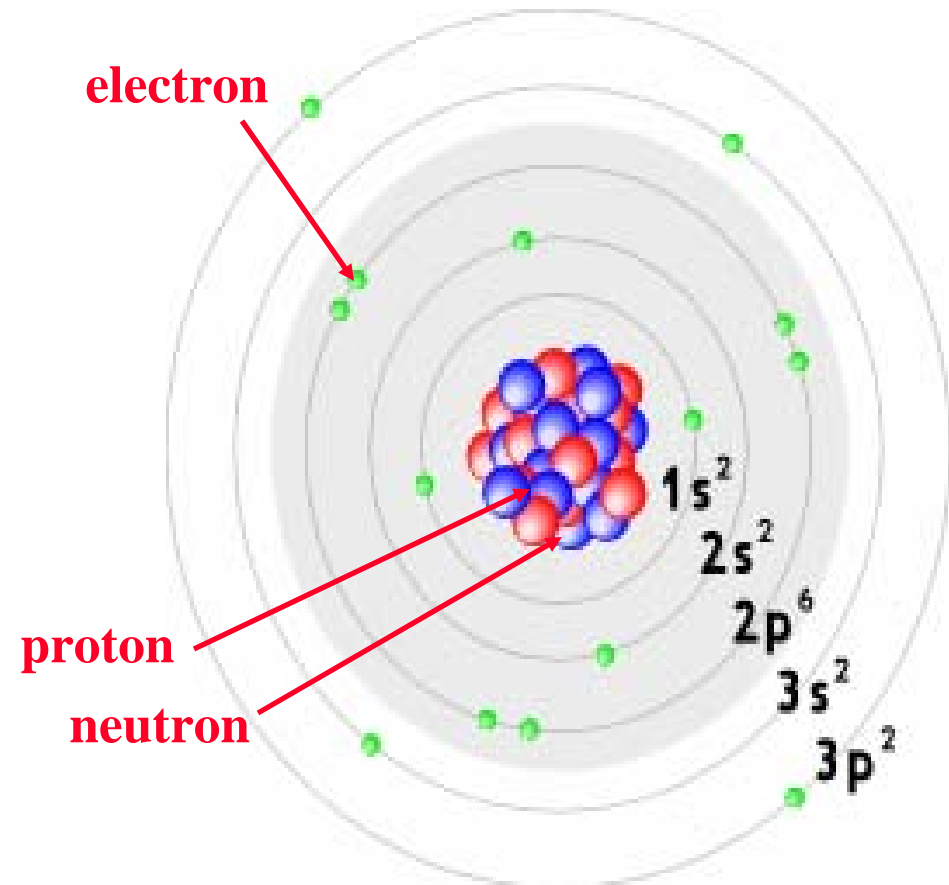
## Outline of Section 3 - Diodes

- Two terminal devices
- Diode models
- Exponential model
- Constant voltage drop model
- Reverse breakdown
- Applications
- Small-signal model
- *PN junctions*



# Silicon

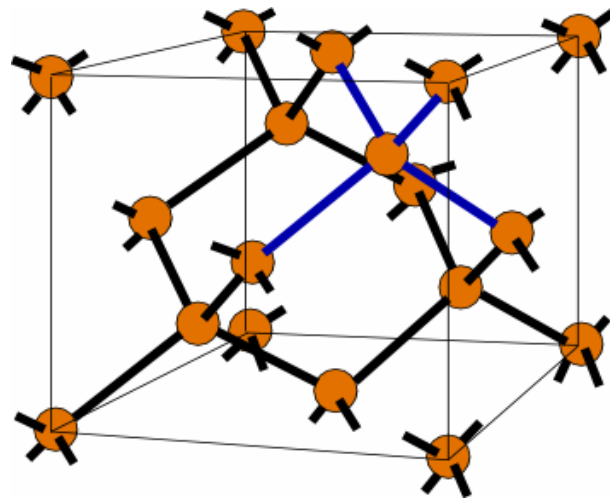
- Silicon
  - Atomic number 14
  - Atomic weight: 28.09au
- The material is the most purified substance man has ever attempted to produce.
- It has 4 valence electrons and if properly grown in crystal-form it takes on a face-body cubic crystal pattern.



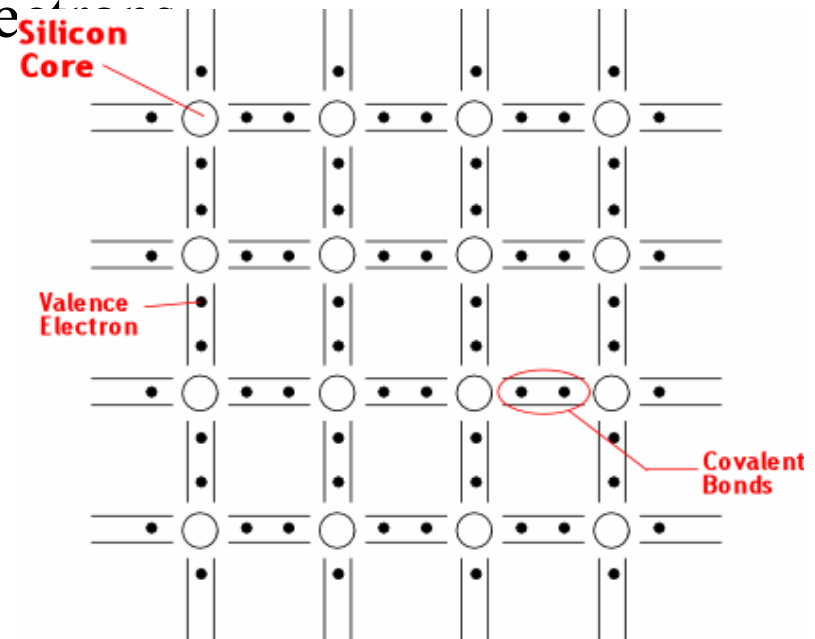


# Silicon Semiconductor

- Intrinsic silicon has a regular crystal lattice of atoms
  - held together by covalent bonds
  - each atom has four valence electrons



$5 \times 10^{22}$  atoms/cm<sup>3</sup>



Rubber

Silicon

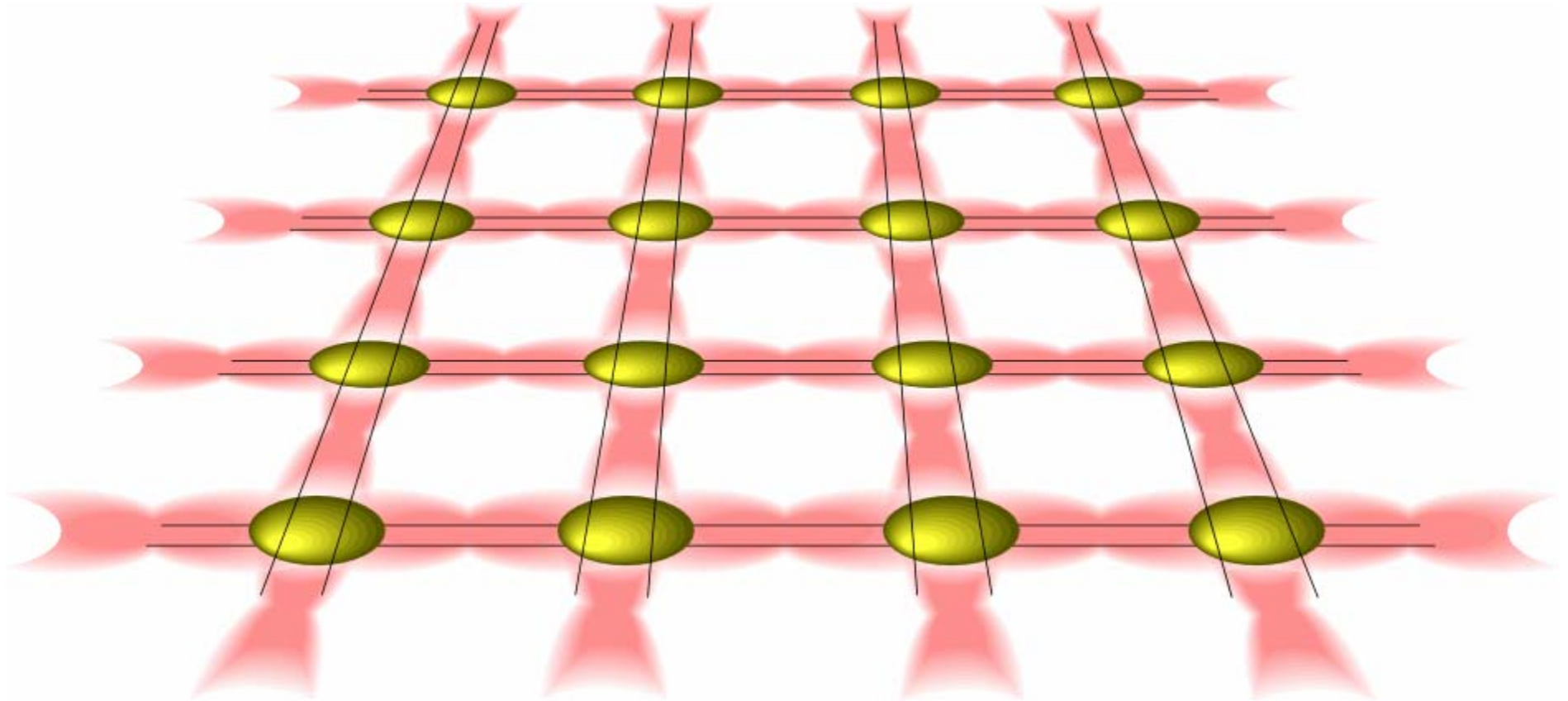
Copper

(semi-conductor)

Diodes 3.74



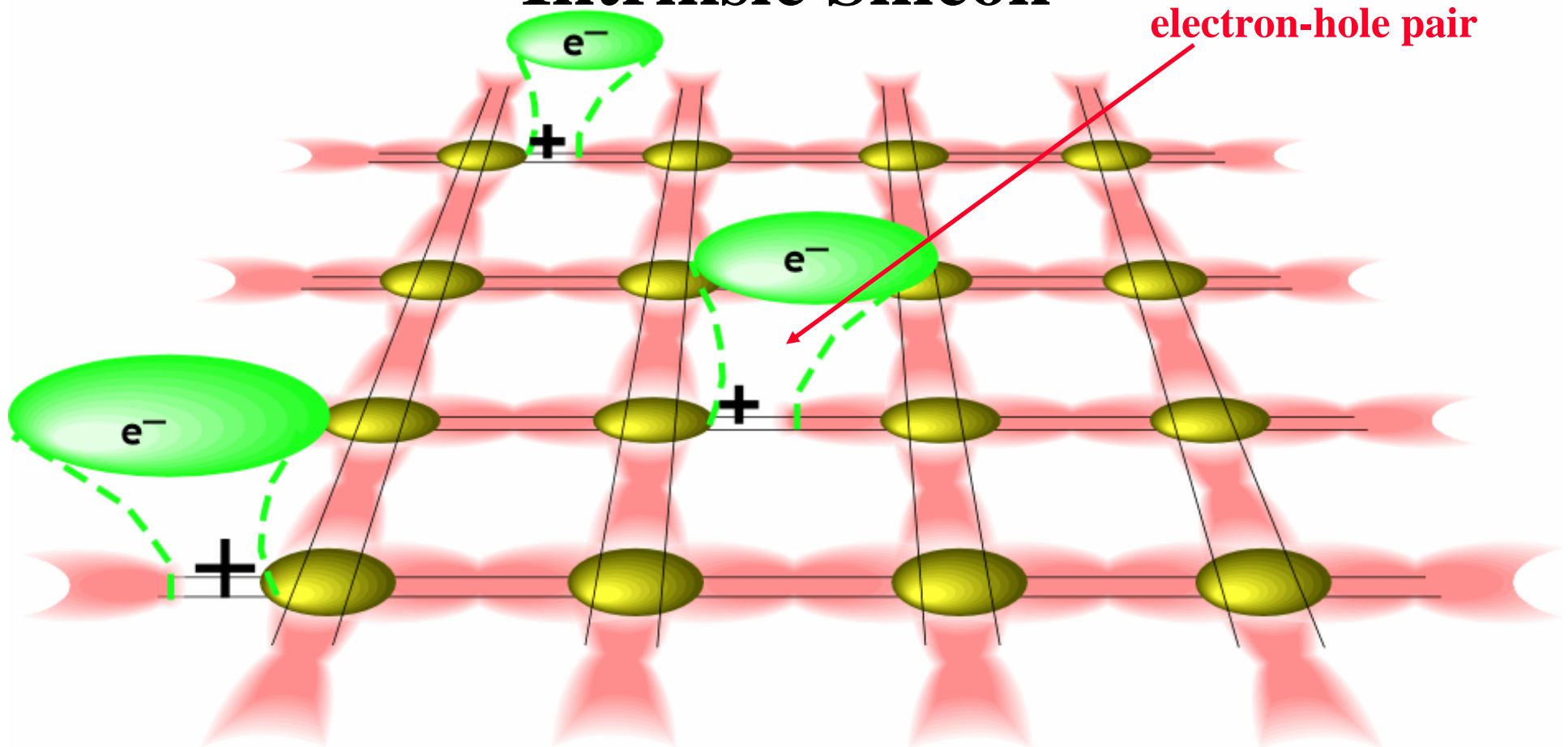
# Intrinsic Silicon



- At low temperatures, all covalent bonds are intact ( $T \rightarrow 0\text{K}$ ), there are no free electrons



# Intrinsic Silicon



- As temperature rises, some electrons break free, leaving *holes* in lattice with positive charge.
- These are called *Electron-hole pairs*. The electrons move in the *conduction-band* and holes move in the *valence-band* Diodes 3.76

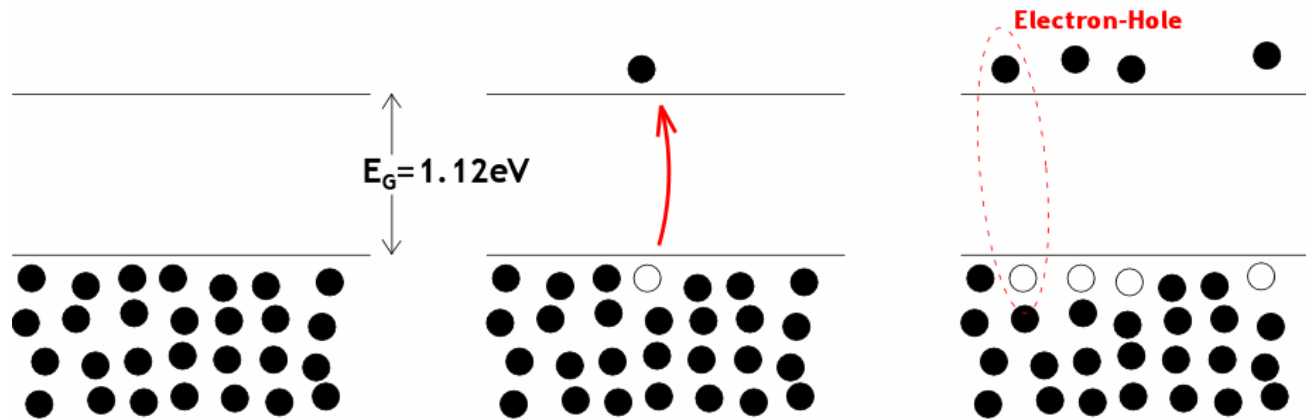


# Intrinsic Silicon

- The number of holes ‘p’ and the number of electrons ‘n’ increases equally with temperature.
- At room-temperature ( $T > 273\text{K}$ ),  $n = p = 1.5 \times 10^{10}$  carriers/cm<sup>3</sup>.

$$n_i = n = p \quad n_i^2 = np$$

## Conduction band

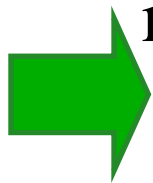


## Valence band

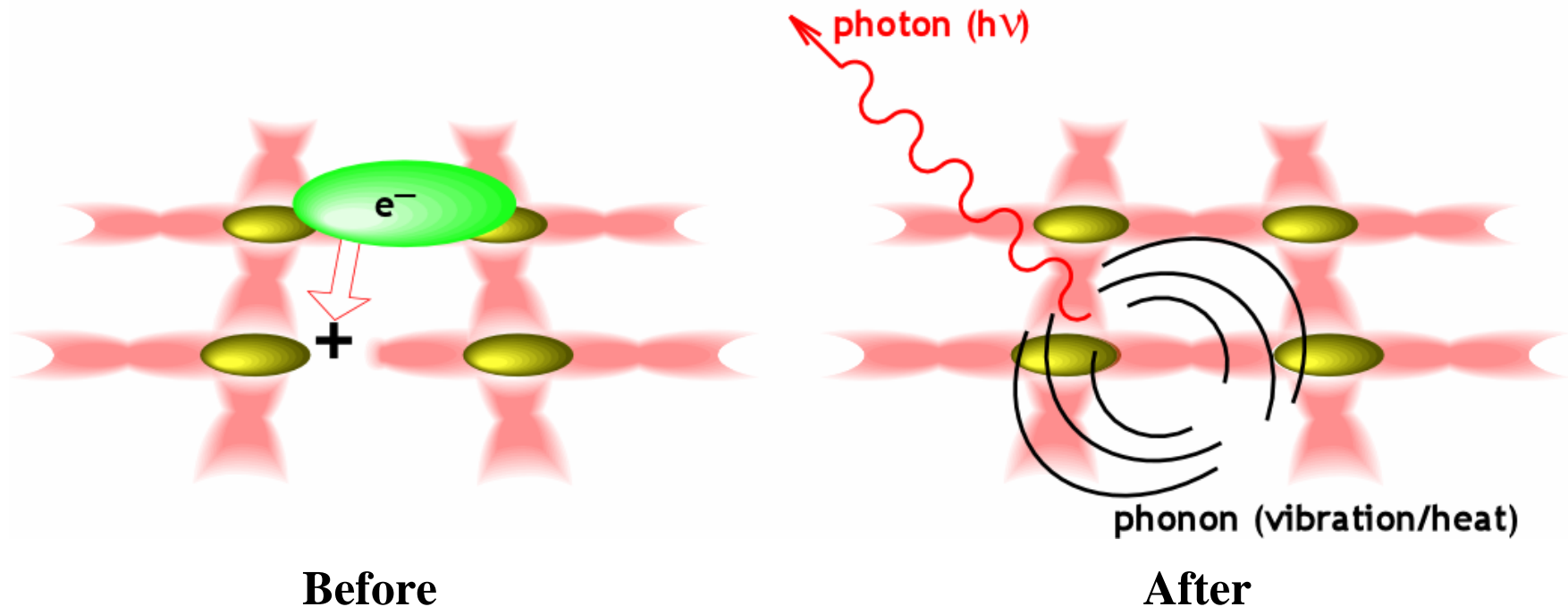


# Electron-Hole Recombination

- Electrons in conduction band and holes in valence band may interact with each other.



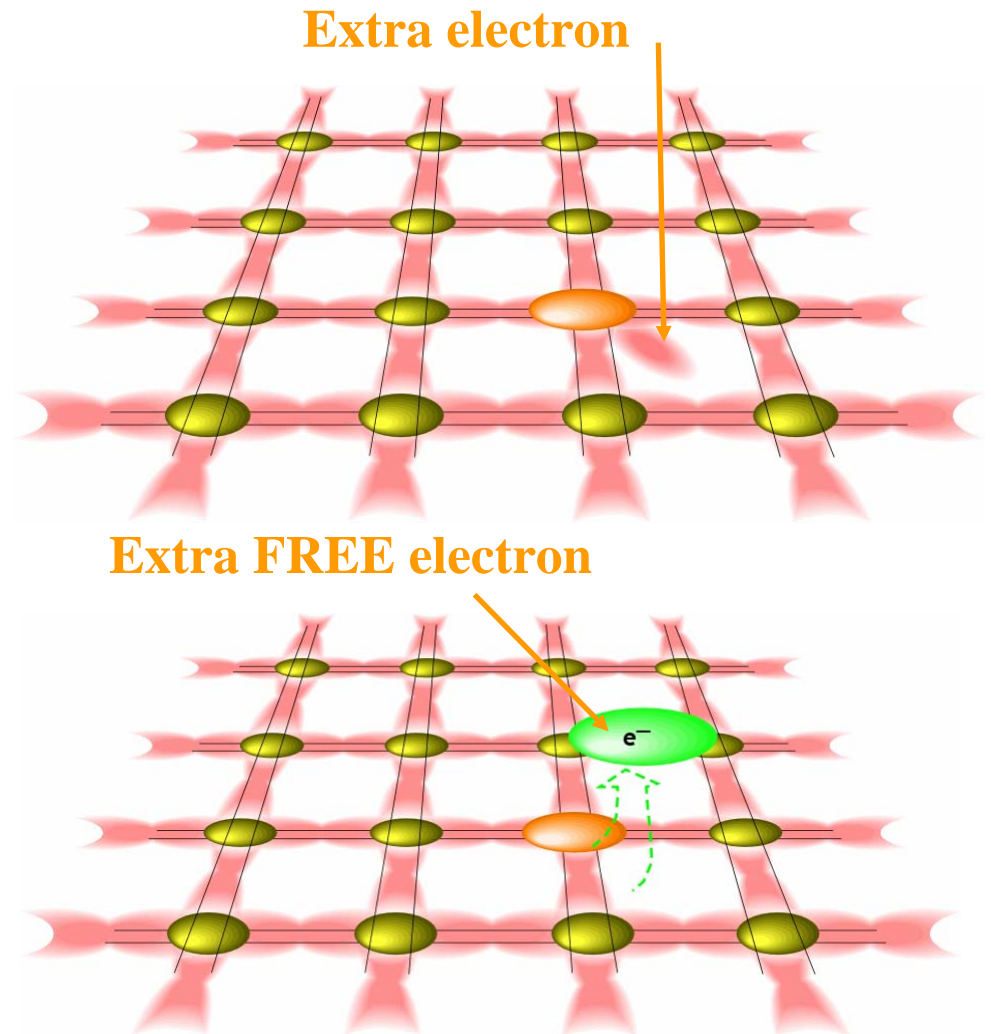
A free electron and a free hole interact and annihilate each other.





# Semiconductor Doping

- Phosphorous-doping
  - This atom has 5 valence electrons.
- This creates a “N-type” semiconductor. It is also called a DONOR atom.
- At room temperature, there is an excess of FREE-electrons.
- If the doping is significant and  $T=273\text{K}$ , then:  $n = N_D$  and  $p = n_i^2/N_D$

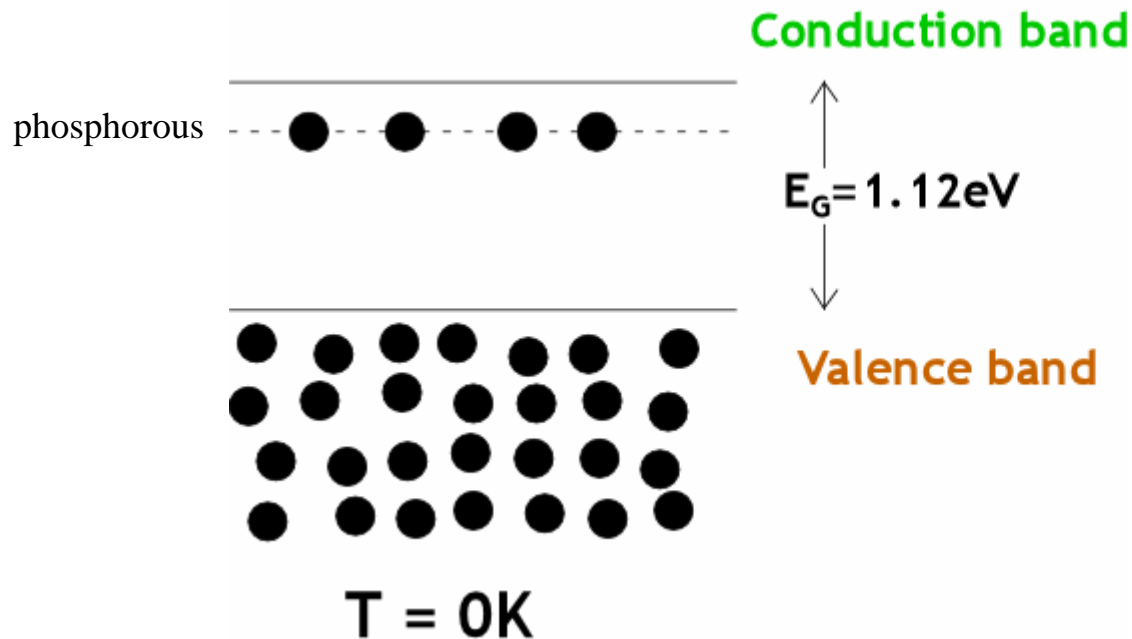






## N-type Silicon

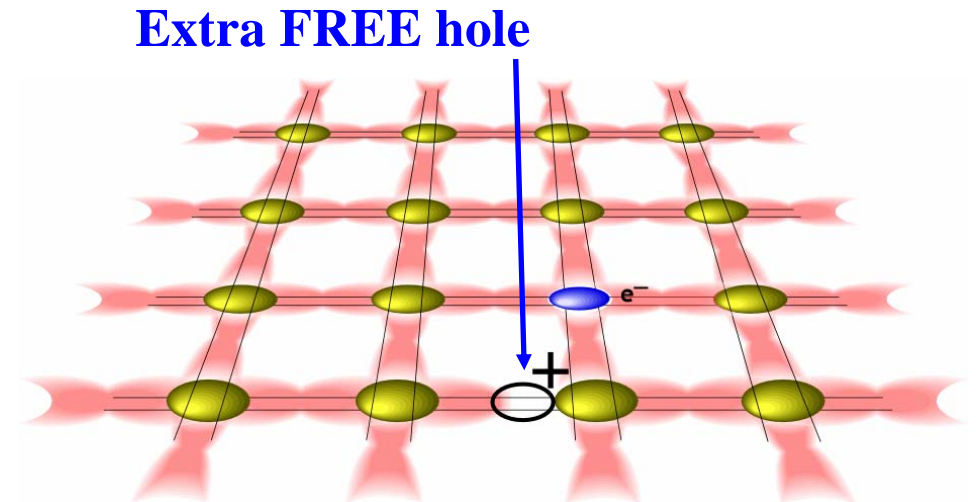
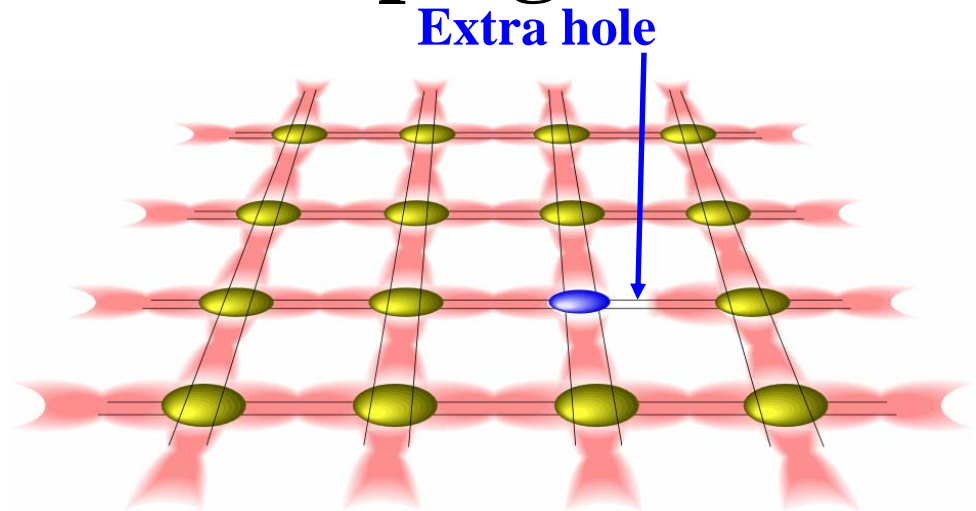
- In n-type silicon:
  - electrons are *majority carriers* and holes are *minority carriers*





# Semiconductor Doping

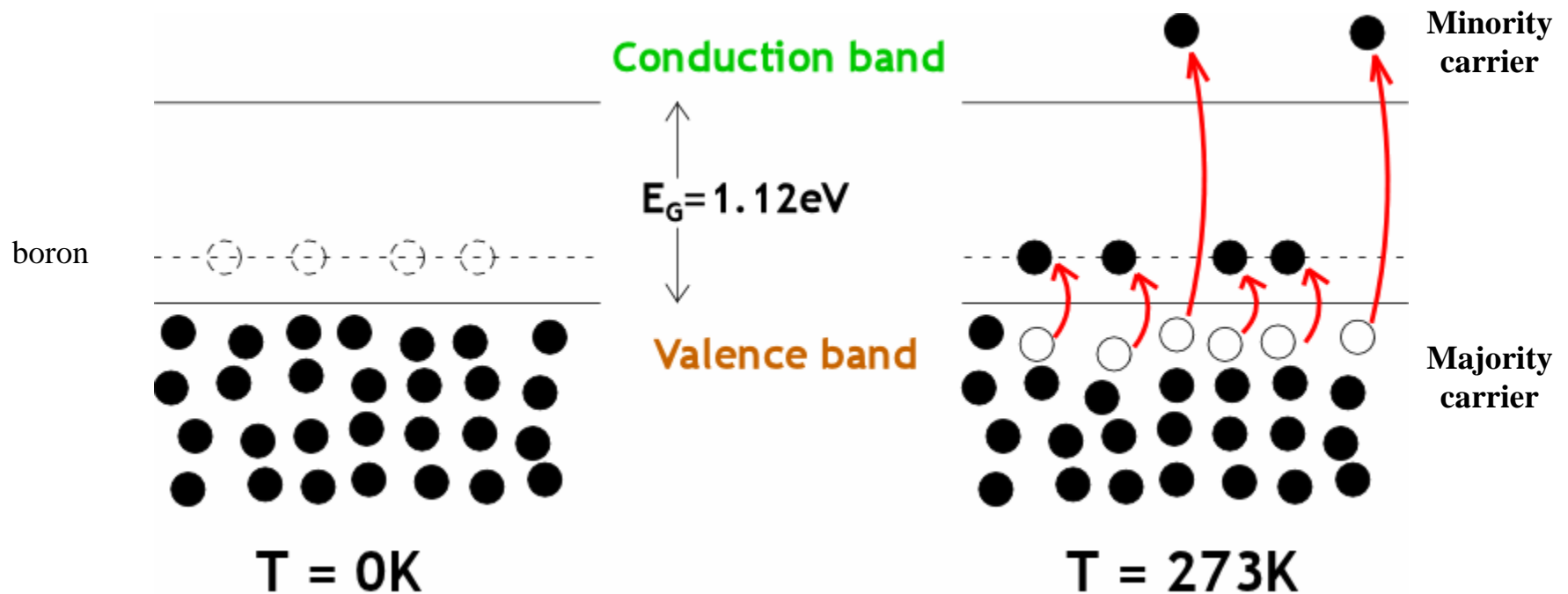
- Boron-doping
  - This atom has 3 valence electrons.
- This creates a “P-type” semiconductor. It is also called a **ACCEPTOR**.
- At room temperature, there is an excess of FREE-holes.
- If the doping is significant and  $T=273\text{K}$ , then:  $p = N_A$  *and*  $n = n_i^2/N_A$





# P-type Silicon

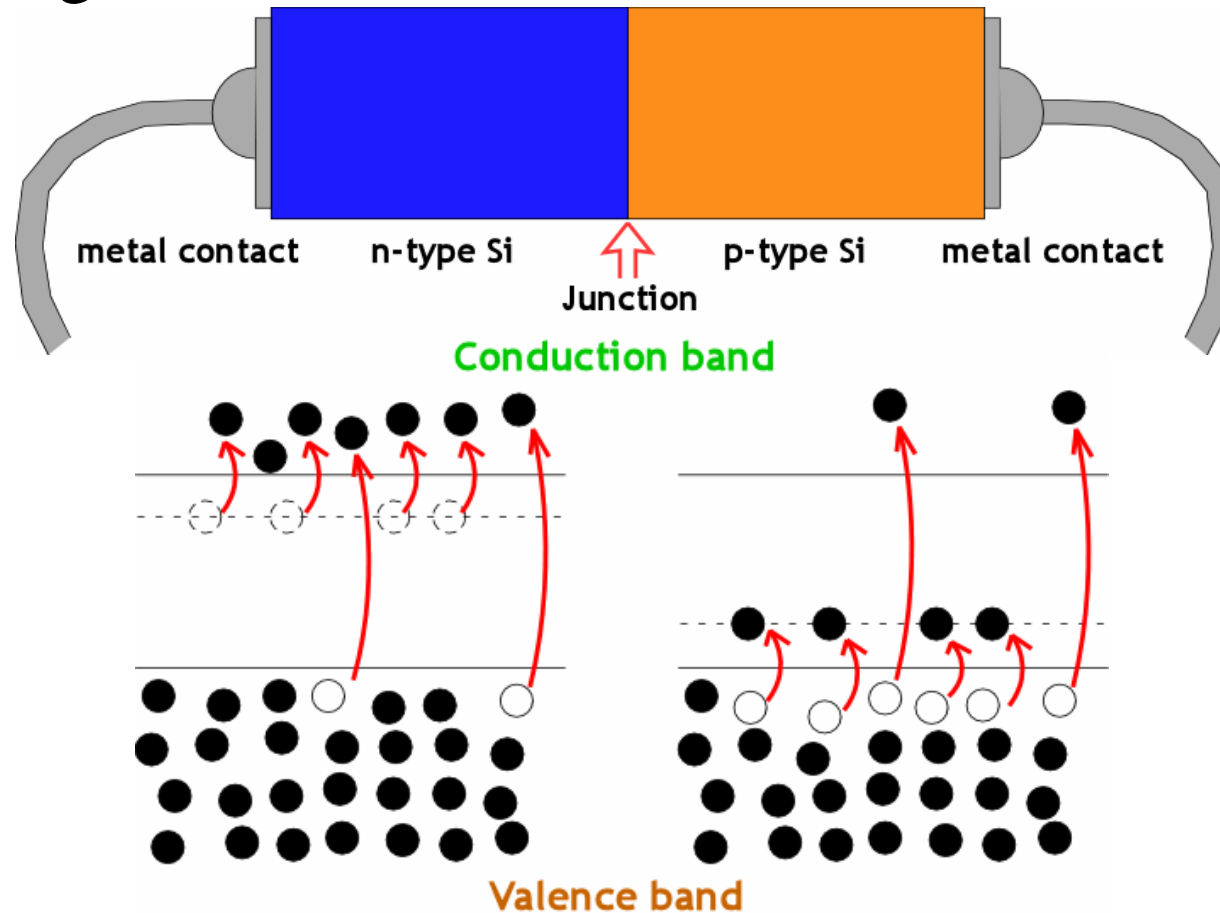
- In p-type silicon:
  - holes are *majority carriers* and electrons are *minority carriers*





# The PN Junction

- When a **p-type** material is brought into contact with an **n-type** material, the interface changes and creates a “built-in” voltage.





# Diffusion of holes and electrons

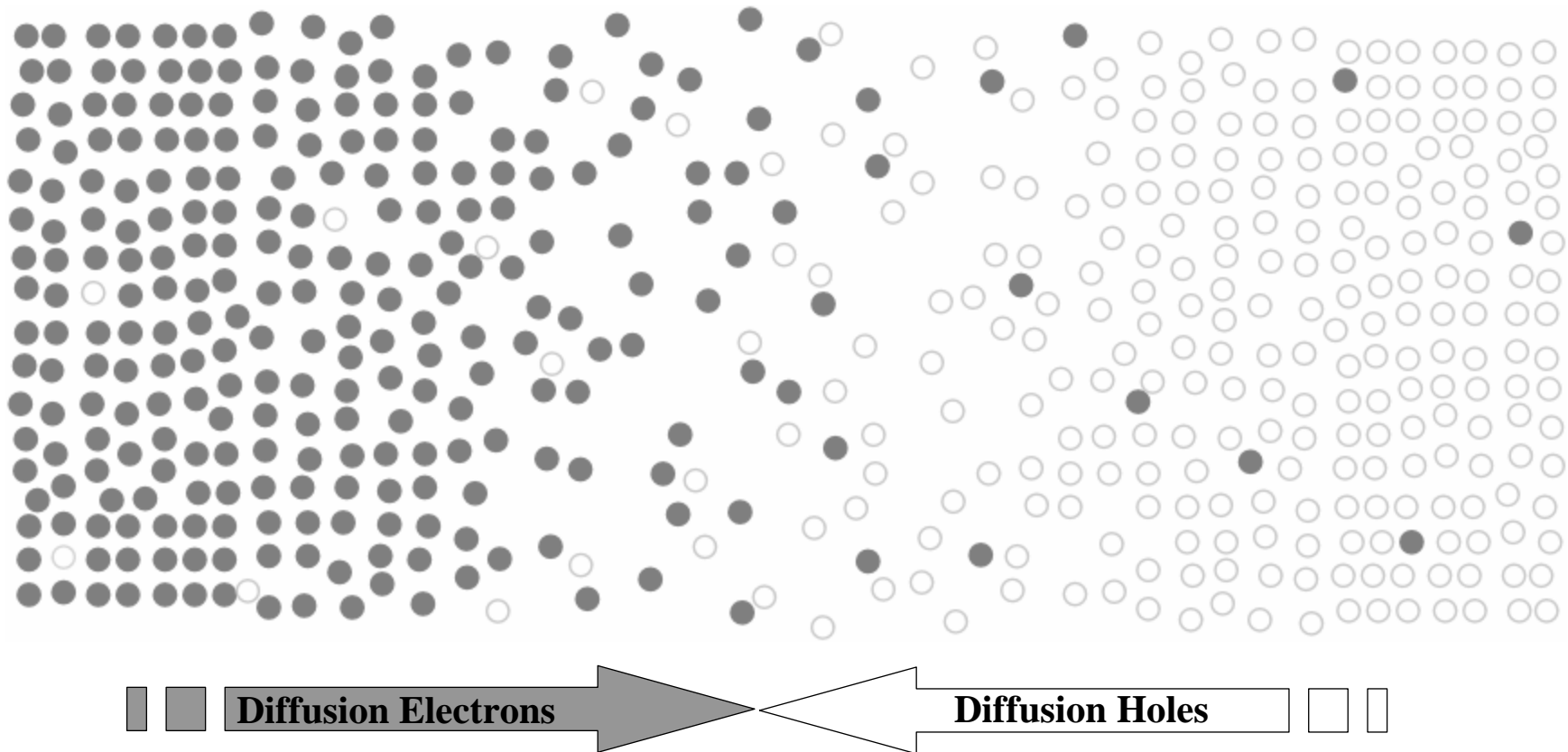
- The FREE electrons from the n-type material diffuse to the right
- Diffusion is part of the thermodynamic law of MAXIMUM ENTROPY



- The FREE holes from the p-type material diffuse to the left
- Just like the way perfume diffuses across a room over time



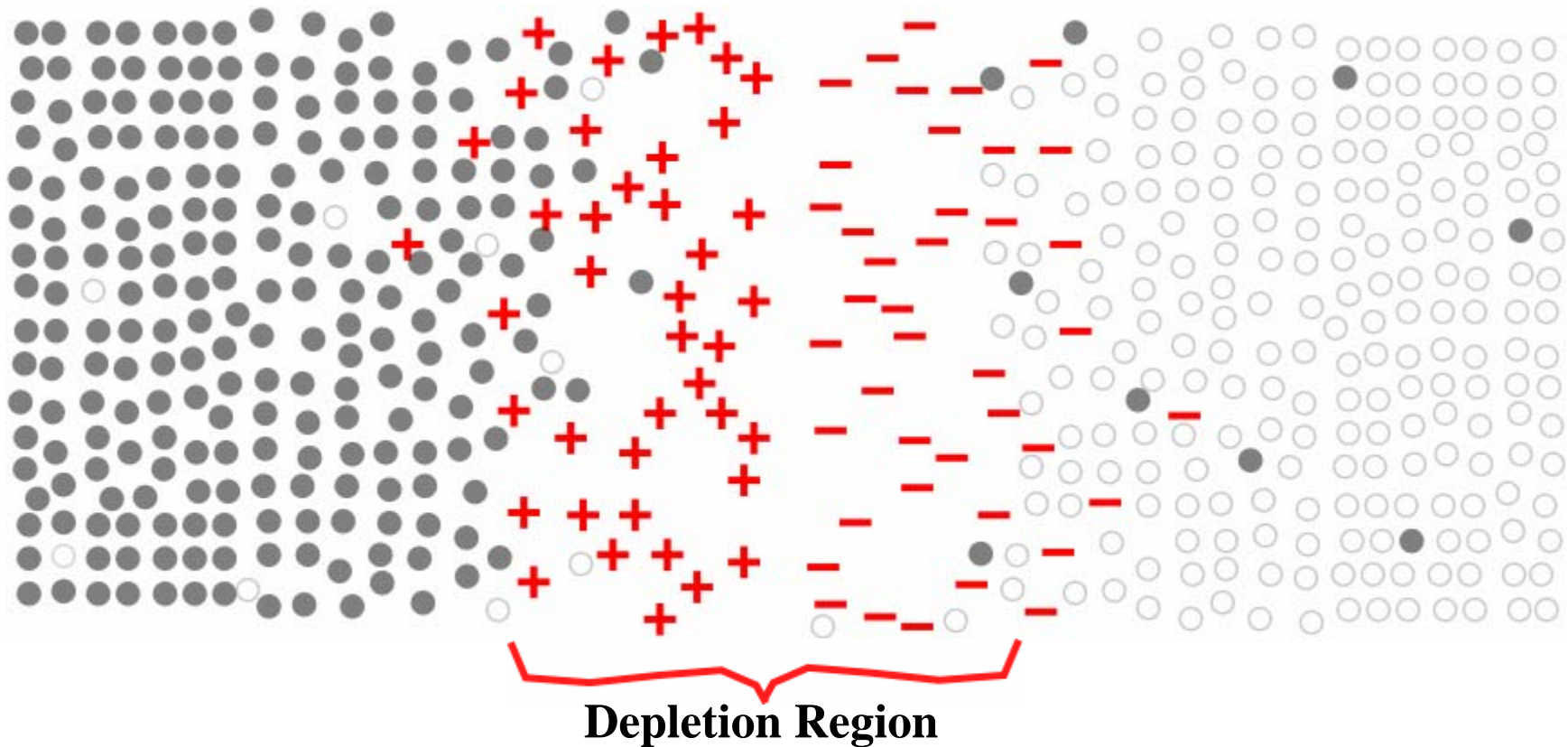
# Diffusion and Drift



- As the carriers diffuse across the junction, they recombine with the majority carriers on the opposite side, this creates local charge sites and a depletion region.



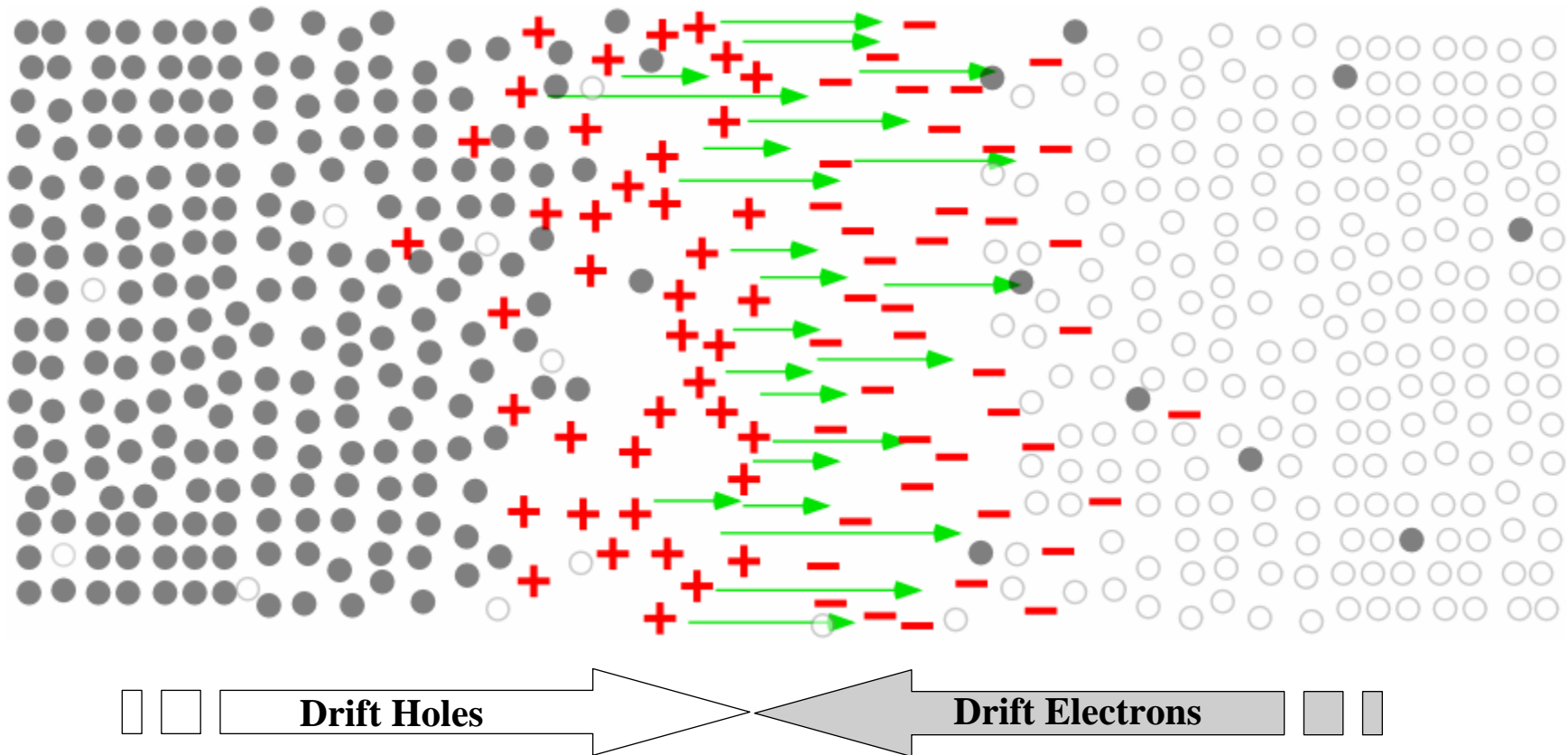
# Diffusion and Drift



- These local charge sites do not move and create an internal electric field. This field is the source of DRIFT for any free carriers that diffuse into the depletion region.



# Diffusion and Drift



- When the rate of Diffusion equals the rate of Drift a steady-state condition is obtained and no more macroscopic changes occur.





# The PN Junction Equations

Diffusion current  $I_{Diff} = qA \left( D_n \frac{dp}{dx} - D_p \frac{dn}{dx} \right)$

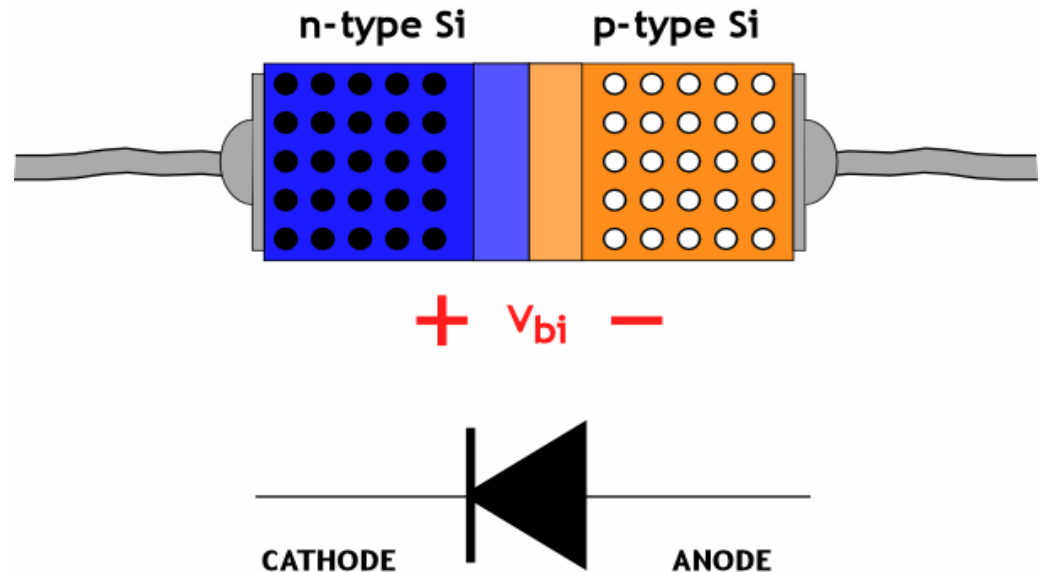
Drift current  $I_{Drift} = qA (p\mu_p + n\mu_n) E$

When the external current  $I = 0$   $I_{Diff} = I_{Drift}$

This produces a built-in voltage of:

$$V_{bi} = V_T \ln \left( \frac{N_A N_D}{n_i^2} \right)$$

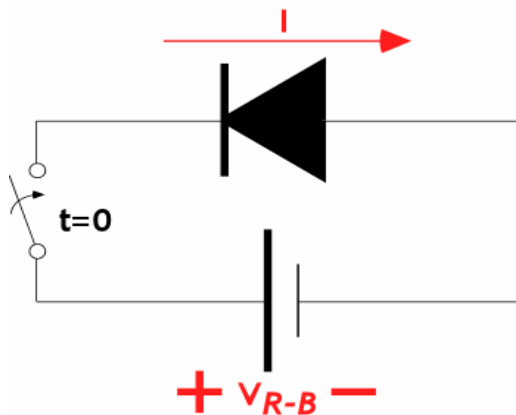
where  $V_T = \frac{kT}{q}$



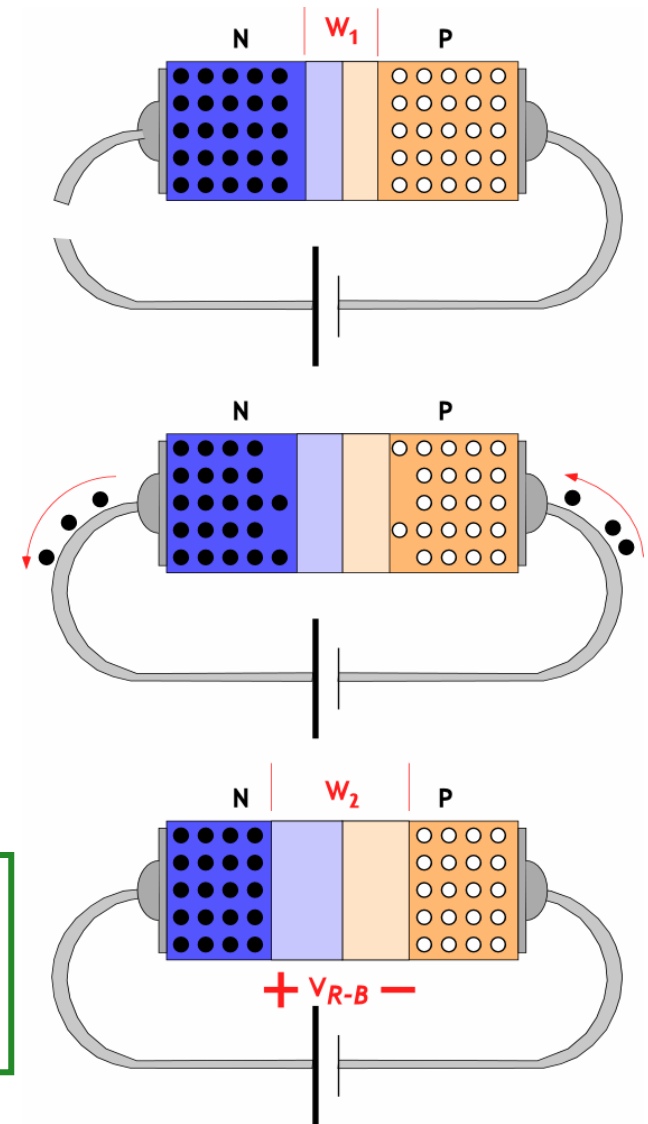


# The PN Junction – Reverse Bias

- When a reverse-bias voltage is applied to junction, depletion-region widens to accommodate the higher reverse-bias.
- As the majority carriers are depleted from the junction, the diffusion current decreases, and the drift current increases until the junction voltage equals the applied reverse-bias. This stops the current.



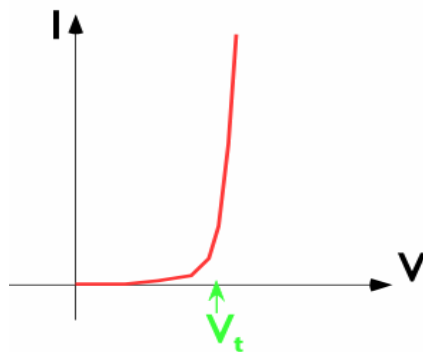
Note: explanation neglects saturation current  $I_s$



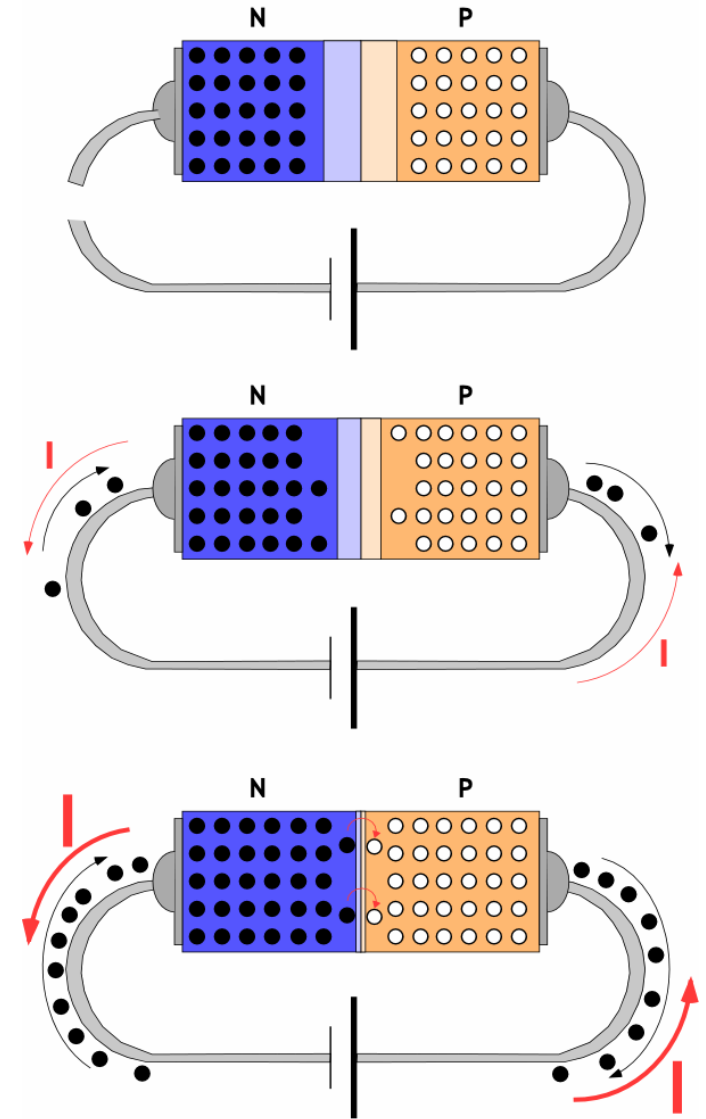


# The PN Junction – Forward Bias

- Forward-bias voltage injects majority carrier electrons into n-type, majority carrier holes into p-type material  
Dominant current is the diffusion current.
- Diffusion of carriers across the junction, and the subsequent recombination completes the circuit.
- The process “takes-off” after 0.7V and collapses the built-in voltage to almost zero.



$$I = I_S \left( e^{v/nV_T} - 1 \right)$$





# The PN Junction – Operational Summary

- Reverse bias operation dominated by:
  - drift current
  - minority carriers in majority type material (e.g. holes in n-type material)
  - magnitude of current flow limited by ability to reduce diffusion effects and onset of breakdown
- Forward bias operation dominated by:
  - diffusion current effects
  - majority carriers in majority type material (e.g. holes in p-type material)
  - magnitude of current flow limited by how many carriers one can shove into the device before it melts



# PN Junction Devices Physics Summary

- Lattice structure of intrinsic silicon
- Electrons and holes in conduction and valence bands
- Recombination
- Doping: n-type and p-type silicon
- Charge carrier motion: diffusion and drift
- Open-circuit p-n junction: diffusion, drift, depletion region, built-in voltage
- Reverse-bias, reverse-breakdown and forward bias operation of pn junction